PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7835685

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YOHSUKE ISHII	01/11/2023
MASAYUKI SAKATA	01/13/2023

RECEIVING PARTY DATA

Name:	HITACHI, LTD.
Street Address:	6-6, MARUNOUCHI 1-CHOME
City:	CHIYODA-KU, TOKYO
State/Country:	JAPAN
Postal Code:	100-8280

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18119035

CORRESPONDENCE DATA

Fax Number: (202)672-5399

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2026725300
Email: sshin@foley.com, ipdocketing@foley.com
Correspondent Name: FOLEY & LARDNER LLP
Address Line 1: 3000 K STREET N.W.
Address Line 2: SUITE 600
Address Line 4: WASHINGTON, D.C. 20007

ATTORNEY DOCKET NUMBER:	093659-0273
NAME OF SUBMITTER:	STEPHANIE SHIN
SIGNATURE:	/Stephanie Shin/
DATE SIGNED:	03/08/2023

Total Attachments: 3
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ASSIGNMENT
（ 譲 渡 証 ）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi, Ltd.,
a corporation organized under the laws of Japan,
located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to saic Hitachi, Ltd.,
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

COMPUTER SYSTEM, DEPLOYMENT PLAN GENERATION METHOD, AND DEPLOYMENT CONTROL SYSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi, Ltd.,
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
1） /Yohsuke Ishii/ Yohsuke ISHII	01/11/2023
2） Masayuki SAKATA	
3）	
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5）	
6）	
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8）	
9）	

10) ______________________________ ______________________________

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its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

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to be held and enjoyed by said Hitachi, Ltd.,
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

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And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
1）	Yohsuke ISHII	
2）	/Masayuki Sakata/ Masayuki SAKATA	01/13/2023
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